

Multi Project Wafer Schedule 2017

X-CMOS 0.18 μm (*)

PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
XH018	05-Sep-16	19-Sep-16	16-Jan-17
XH018	07-Nov-16	20-Nov-16	20-Mar-17
XH018	04-Jan-17	18-Jan-17	31-May-17
XH018	08-May-17	22-May-17	02-Oct-17
XH018	04-Aug-17	18-Aug-17	29-Dec-17
XH018	13-Nov-17	27-Nov-17	09-Apr-18

Available metal stack options for XH018 MPW runs:

4 Metal Layers: MET1-MET2-MET3-METMID; MIM or MIMH are optional capacitor modules

6 Metal Layers: MET1-MET2-MET3-MET4-METMID-METTHK; MIM or MIMH are optional capacitor modules

PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
XP018	24-Oct-16	07-Nov-16	27-Feb-17
XP018	13-Feb-17	27-Feb-17	03-Jul-17

PROCESS	TAPE-IN	DATA RELEASE		SAMPLES OUT
XP018	19-Jun-17	03-Jul-17	06-Nov-17	
XP018	23-Oct-17	06-Nov-17	12-Mar-18	

Available metal options for XP018 MPW runs:

4 Metal Layers: MET1-MET2-MET3-METMID; MIM or MIMH are optional capacitor modules

6 Metal Layers: MET1-MET2-MET3-MET4-METMID-METTHK; MIM or MIMH are optional capacitor modules

PROCESS	TAPE-IN	DATA RELEASE		SAMPLES OUT
XT018	26-Sep-16	10-Oct-16		17-Mar-17**
XT018	31-Jan-17	14-Feb-17		18-Jul-17**
XT018	27-Mar-17	10-Apr-17		25-Sep-17**
XT018	22-May-17	05-Jun-17		20-Nov-17**
XT018	24-Jul-17	07-Aug-17		22-Jan-18**
XT018	02-Oct-17	16-Oct-17		02-Apr-18**

**THKCOP module is not available for this MPW run.

Available metal stack options for XT018 MPW runs:

PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
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4 Metal Layers: MET1-MET2-MET3-METTHK; MIMH as optional capacitor module

6 Metal Layers: MET1-MET2-MET3-MET4-METMID-METTHK; MIM or MIMH are optional capacitor modules

PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
XS018	07-Oct-16	21-Oct-16	06-Feb-17**
XS018	06-Mar-17	20-Mar-16	24-Jul-17**
XS018	04-Sep-17	18-Sep-17	22-Jan-18**

****This MPW run covers only a restricted set of modules. Only limited LVT & PPD option will be offered. Please check with your X-FAB contact prior to tape-in.**

Available metal stack options for XS018 MPW runs:

4 Metal Layers: MET1-MET2-MET3-METTHIN; MIM23 or MIMH23 are optional capacitor modules

6 Metal Layers: MET1-MET2-MET3-MET4-MET5-METMID; MIM or MIMH are optional capacitor modules

X-CMOS 0.35 μm (*)

PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
XH035	18-Nov-16	02-Dec-16	29-Mar-17
XH035	20-Jan-17	03-Feb-17	02-Jun-17

PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
XH035	12-May-17	26-May-17	22-Sep-17
XH035	18-Aug-17	01-Sep-17	29-Dec-17
XH035	17-Nov-17	01-Dec-17	30-Mar-18

Additional runs available on request.

Usable modules: MOS, ISOMOS, THK0X, NMVMOS, PMVMOS, HVMOSMID, DEPL, BURDIF, CAPPOLY, HRPOLY, XRPOLY, TEEPROM, MIM, DMIM, METAL2, THKMET3, METAL4, THKMET, OTP, NHVETHK, PHVEMID, PHVETHK, NHVEMID

X-CMOS 0.6 μm (*)

PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
XC06	24-Oct-16	07-Nov-16	08-Feb-17
XC06	06-Jan-17	20-Jan-16	21-Apr-17
XC06	16-Jun-17	30-Jun-17	29-Sep-17
XC06	20-Oct-17	03-Nov-17	02-Feb-18

X-DIMOS 1.0 μm (*)

PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
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PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
XDH10/XDM10	10-Mar-17	24-Mar-17	26-May-17
XDH10/XDM10	08-Sep-17	22-Sep-17	24-Nov-17